

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY DOCKET NO.	SERIAL NO.
	SIO9-2000-0067US1	09/764,019
	APPLICANT	
	Hsiao et al.	
	FILING DATE	GROUP
	January 16, 2001	2652

U. S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>RST</i>	AA	5,047,115	9/1991	Charlet et al.	156	643	
<i>RST</i>	AB	5,356,478	10/1994	Chen et al.	134	1	
<i>RST</i>	AC	6,260,256 B1	7/2001	Sasaki	29	603.01	
	AD						
	AE						
	AF						
	AG						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUBCLASS	TRANSLATION YES NO
<i>RST</i>	AH	02230505	9/1990	Japan	NEC Corp.	G11B	5/31	X
<i>RST</i>	AI	11283216	10/1999	Japan	TDK Corp.	G11B	5/31	X
<i>RST</i>	AJ	PCT/EP01/15254						
	AK							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AL		
	AM		

EXAMINER	<i>R.S. TURNER</i>	DATE CONSIDERED	<i>8/04</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY DOCKET NO. SIO9-2000-0067US1	SERIAL NO. Unassigned
	APPLICANT Hsiao et al.	
	FILING DATE January 16, 2001	GROUP Unassigned

U. S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>RST</i>	AA	5,059,278	10/1991	Cohen et al.	156	643	
	AB						
	AC						
	AD						
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	AI						
	AJ						
	AK						

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	AL							
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	AN							
	AO							
	AP							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>RST</i>	AQ		IBM Technical Disclosure Bulletin, Nov. 1992, "Alternate Method for Etching Copper Seed Layers."
<i>RST</i>	AR		IBM Technical Disclosure Bulletin, June 1995, "NiFe/Cu Seed Layer for Plating Coil Cu in Magnetic Recording Heads."
	AS		

EXAMINER <i>R. S. Tamm</i>	DATE CONSIDERED <i>8/04</i>
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